TOSHIBA Field Effect Transistor Silicon P Channel MOS Type (U-MOS III)

# **TPCF8102**

#### Notebook PC Applications Portable Equipment Applications

- Low drain-source ON resistance:  $RDS(ON) = 24 \text{ m}\Omega$  (typ.)
- High forward transfer admittance:  $|Y_{fs}| = 14 \text{ S} (typ.)$
- Low leakage current:  $I_{DSS} = -10 \ \mu A \ (max) \ (V_{DS} = -20 \ V)$
- Enhancement mode:  $V_{th} = -0.5$  to -1.2 V
  - $(V_{DS} = -10 \text{ V}, \text{ I}_{D} = -200 \text{ }\mu\text{A})$

#### Absolute Maximum Ratings (Ta = 25°C)

Characte	ristics	Symbol	Rating	Unit
Drain-source voltage		V <sub>DSS</sub>	-20	V
Drain-gate voltage (R	<sub>GS</sub> = 20 kΩ)	V <sub>DGR</sub>	-20	V
Gate-source voltage		V <sub>GSS</sub>	±8	V
Drain current	DC (Note 1)	I <sub>D</sub>	-6	А
Drain current	Pulsed (Note 1)	I <sub>DP</sub>	-24	~
Drain power dissipation	on (t = 5 s) (Note 2a)	PD	2.5	W
Drain power dissipation	on (t = 5 s) (Note 2b)	PD	0.7	W
Single pulse avalanch	ne energy(Note 3)	E <sub>AS</sub>	5.9	mJ
Avalanche current		I <sub>AR</sub>	-3	А
Repetitive avalanche	energy (Note 4)	E <sub>AR</sub>	0.25	mJ
Channel temperature		T <sub>ch</sub>	150	°C
Storage temperature	range	T <sub>stg</sub>	-55~150	°C



Weight: 0.011 g (typ.)

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

#### **Thermal Characteristics**

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to ambient $(t = 5 s)$ (Note 2a)	R <sub>th (ch-a)</sub>	50.0	°C/W
Thermal resistance, channel to ambient $(t = 5 s)$ (Note 2b)	R <sub>th (ch-a)</sub>	178.6	°C/W

#### **Circuit Configuration**



Note: (Note 1), (Note 2), (Note 3), (Note 4) and (Note 5): See the next page. This transistor is an electrostatic-sensitive device. Please handle with caution. Unit: mm

## **Electrical Characteristics (Ta = 25°C)**

Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit	
Gate leakage current		I <sub>GSS</sub>	$V_{GS} = \pm 8 \text{ V},  V_{DS} = 0 \text{ V}$		_	±10	μA	
Drain cut-off current		I <sub>DSS</sub>	$V_{DS} = -20 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$	_	_	-10	μA	
Drain-source breakdown voltage		V (BR) DSS	$I_D = -10$ mA, $V_{GS} = 0$ V	-20	—	_	v	
		V (BR) DSX	$I_D = -10$ mA, $V_{GS} = 8$ V	-12	_	_		
Gate threshold ve	oltage	V <sub>th</sub>	$V_{DS} = -10 \text{ V}, \text{ I}_{D} = -200 \mu\text{A}$	-0.5	_	-1.2	V	
Drain-source ON resistance		R <sub>DS (ON)</sub>	$V_{GS} = -1.8 \text{ V}, I_D = -1.5 \text{ A}$	_	67	90		
		R <sub>DS (ON)</sub>	$V_{GS} = -2.5 \text{ V}, \text{ I}_{D} = -3.0 \text{ A}$	_	36	41	mΩ	
		R <sub>DS (ON)</sub>	$V_{GS} = -4.5 \text{ V}, \text{ I}_{D} = -3.0 \text{ A}$	_	24	30		
Forward transfer admittance		Y <sub>fs</sub>	$V_{DS} = -10 \text{ V}, \text{ I}_{D} = -3.0 \text{ A}$	7	14	_	S	
Input capacitance		C <sub>iss</sub>		_	1550	_	pF	
Reverse transfer capacitance		C <sub>rss</sub>	$V_{DS} = -10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		215			
Output capacitance		C <sub>oss</sub>			265			
Switching time	Rise time	tr	$V_{GS} \xrightarrow{0 V} I_D = -3.0 \text{ A}$	_	7	_		
	Turn-on time	t <sub>on</sub>		_	13	_	ns	
	Fall time	tf	R_ = 3.33 f	_	21	_		
	Turn-off time	t <sub>off</sub>	$V_{DD}\simeq -10~V \label{eq:DD}$ Duty $\leq$ 1%, $t_W=10~\mu s$	—	68	_		
Total gate charge (gate-source plus gate-drain)		Qg	$V_{DD} \simeq -16 \text{ V}, \text{ V}_{GS} = -5 \text{ V},$	—	19	—		
Gate-source charge		Q <sub>gs</sub>	$I_{\rm D} = -6.0  {\rm A}$	_	14		nC	
Gate-drain ("miller") charge		Q <sub>gd</sub>			5			

### Source-Drain Ratings and Characteristics (Ta = 25°C)

Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Drain reverse current	Pulse (Note 1)	I <sub>DRP</sub>	—	_	_	-24	А
Forward voltage (diode)		V <sub>DSF</sub>	$I_{DR} = -6.0 \text{ A}, V_{GS} = 0 \text{ V}$	_	_	1.2	V

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#### Marking (Note 5)



Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2: (a) Device mounted on a glass-epoxy board (a)

(b) Device mounted on a glass-epoxy board (b)



Note 3:  $V_{DD} = -16 \text{ V}, \text{ T}_{ch} = 25^{\circ}\text{C}$  (initial), L = 0.5 mH, R<sub>G</sub> = 25  $\Omega$ , I<sub>AR</sub> = -3.0 A

Note 4: Repetitive rating: pulse width limited by maximum channel temperature

Note 5: A dot on the lower left of the marking indicates Pin 1.

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